

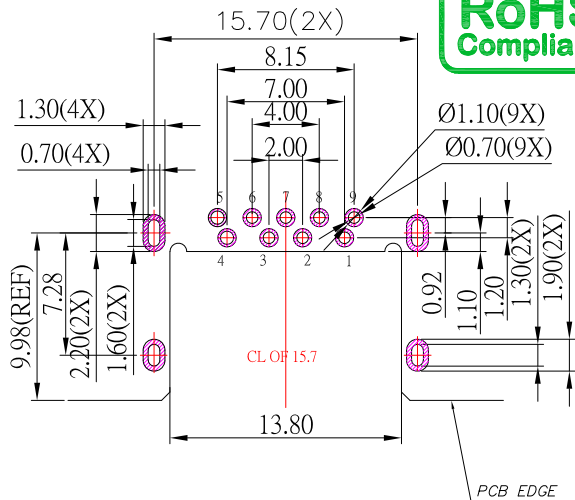
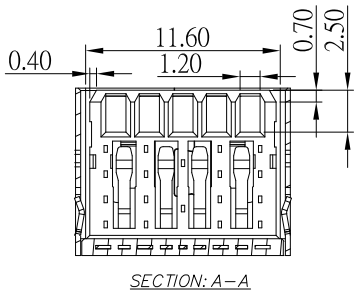
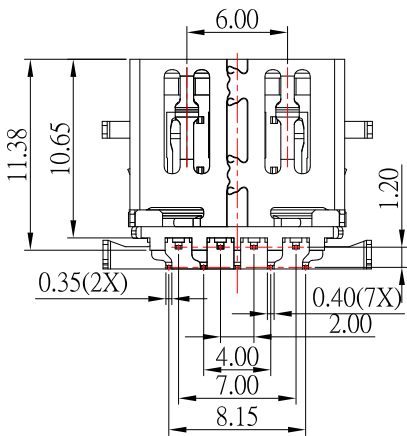
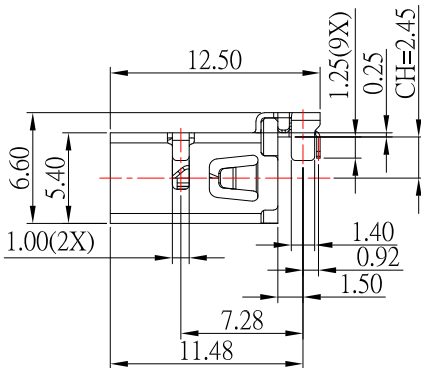
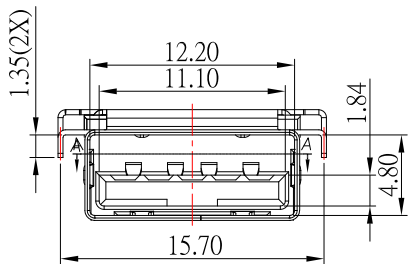
SUA-110E27-30xx-S277

鍍層厚度 :

Blank : 1u"
2 : 15u"
3 : 30u"

HOUSING :

Blank : Blue
B : BLack



PCB LAYOUT

NOTE:

1.MATERIAL:

- 1.1 Housing: LCP
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Rate: 30V DC , 1.8 A
- 3.2 insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 100V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -55°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N

PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME	DESCRIPTION
1	VBUS	POWER
2	D-	USB 2.0 DIFFERENTIAL PAIR
3	D+	
4	GND	GROUND FOR POWER RETURN
5	StdA-SSR-	SUPER-SPEED RECEIVER DIFFERENTIAL PAIR
6	StdA-SSR+	
7	GND-DRAIN	GROUND FOR SIGNAL RETURN
8	StdA-SST-	SUPER-SPEED TRANSMITTER DIFFERENTIAL PAIR
9	StdA-SST+	
SHELL	SHIELD	CONNECTOR METAL SHELL

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 01/08/26
DATE: 01/08/26
DATE: 01/08/26

MAT'L
FINISH
SCALE
SHEET NO.

1 : 1
1 of 1

TITLE: CONNECTOR
MODLE: USB AF 3.0反向無捲邊 DIP 沉板 ,CH2.45 板上H1.45mm
DWG NO.: SUA-110E27-30xx-S277
PART NO.: SUA-110E27-30xx-S277

SIZE: A4
VER: R